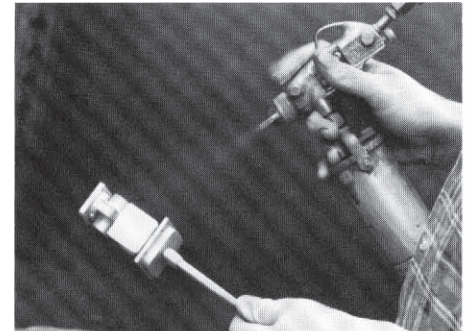


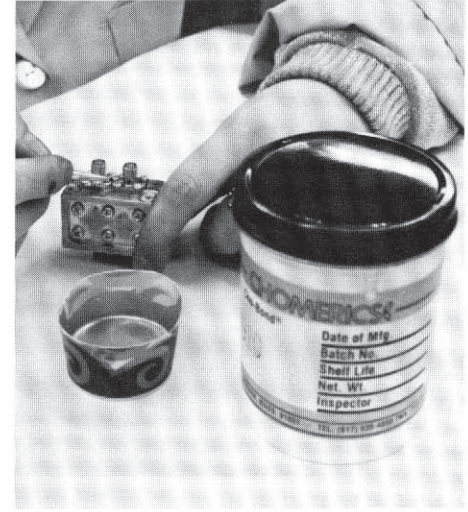
# CHO-BOND® 592

## CONDUCTIVE EPOXY ADHESIVE



### Customer Value Proposition:

CHO-BOND® 592 is a highly conductive silver-filled epoxy adhesive which combines the best properties of metals and organics. This two-component system is unique in that it combines long pot life, good electrical conductivity, excellent adhesion, low temperature cure, easy mix ratio, low viscosity, low coefficient of thermal expansion, very low thermal impedance and good thermal shock resistance. It may be thinned with toluene for spray application.



### Typical Applications:

- Connects dissimilar materials electrically and thermally
- Excels as a sealant for microwave modules and components
- Ideal for circuit board repair and ground ing applications
- Useful for EMI shielding applications

### Contact Information:

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Table 1 Typical Properties

CHO-BOND 592	
Typical Properties	Typical Values
Specific Gravity	2.6 ± 0.25
Volume Resistivity	0.05 ohm-cm
Pot Life	@25 °C (77 °F): 4-6 hrs @5 °C (41 °F) 48 hrs
Shelf Life @ 25 °C (77 °F)	9 months
Lap Shear Strength	1500 psi (105kg/cm <sup>2</sup> )
Mix Ratio, A : B (by weight)	100:50
Curing Schedules	60 min @ 80 °C (176 °F) 30 min @ 100 °C (212 °F) 15 min @ 125 °C (257 °F) 5 min @ 150 °C (302 °F)
Room Temperature Cure 25 °C (77 °F)	1 week*

\* CHO-BOND 592 may be cured at room temperature, but there will be a sacrifice in electrical conductivity.

Authorized Distributor



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